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(71) Applicant *(for all designated States except US)*: **INTERNATIONAL BUSINESS MACHINES CORPORATION** [US/US]; New Orchard Road, Armonk, NJ 10504 (US).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **CHAUDHARI, Praveen** [US/US]; 416 Long Hill Road East, Briarcliff Manor, NY 10510 (US).

(74) Agent: **HOWARD, James, E.**; McGinn & Gibb, PLLC, 8321 Old Courthouse Road, Suite 200, Vienna, VA 22182-3817 (US).

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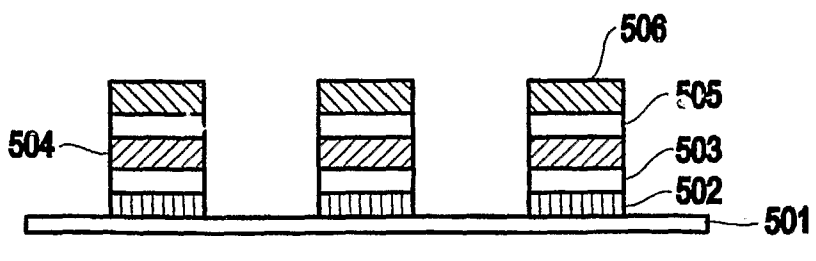
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(54) Title: METHOD OF SELF-ASSEMBLING ELECTRONIC CIRCUITRY AND CIRCUITS FORMED THEREBY



(57) Abstract: A method of assembling a circuit includes providing a template, enabling a semiconductor material to self assemble on the template, and enabling self-assembly of a connection between the semiconductor material and the template to form the circuit and a circuit created by self-assembly.